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Linda Bal is a senior analyst with TechSearch International, Inc., which has provided market research and technology trend analysis in semiconductor packaging since 1987. Linda has more than 25 years of experience in the design, test, and manufacturing of electronic packaging for semiconductors and systems while at Freescale, Motorola, Microelectronics and Computer Technology Corporation (MCC), and Eastman Kodak. Linda has authored and co-authored numerous publications. She is co-author of “New Frontiers in Automotive Electronics Packaging,” a major research study published in 2018 by TechSearch International. A member of IEEE and IMAPS, Linda received her BSEE degree from Purdue University.